

42390.P9557

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Mu, et al.

Serial No.: 09/661,899 ✓

Filed: September 14, 2000

For: PROCESS FOR FORMING A
DIRECT BUILD-UP LAYER ON AN
ENCAPSULATED DIE PACKAGES
UTILIZING INTERMEDIATE
STRUCTURES (As Amended)

Examiner: A. Chambliss

Group Art Unit: 2814

Attorney Docket No.: 42390.P9557

CERTIFICATE OF MAILING

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DEREK L. HIGHAM
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PRELIMINARY AMENDMENT

Hon. Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to the examination of the claims on the merits, Applicants respectfully request that the Examiner enter the following amendments:

IN THE SPECIFICATION:

Please delete the title on the cover page and replace with:

PROCESS FOR FORMING A DIRECT BUILD-UP LAYER ON AN
ENCAPSULATED DIE PACKAGES UTILIZING INTERMEDIATE STRUCTURES